

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-16. (canceled)

17. (currently amended) A manufacture comprising:

- a) a dielectric substrate having a first surface, a second surface, and one or more vias between the surfaces,
- b) a metal pattern on the first surface ~~contacting the vias, and~~ including one or more bonding pads covering the vias,
- c) a solderable metal member within the vias forming the bottom surface of a solid column of conductive material, the column filling the via and connecting the metal pattern, and
- d) a solder ball extending into a via from the second surface, contacting the solderable metal member at an end of the solid column.

18. (new) The manufacture of claim 17, in which the solid column comprises copper.

19. (new) The manufacture of claim 17, in which the solid column comprises nickel.

20. (new) The manufacture of claim 17, in which the solid column comprises nickel and copper.

22. (new) The manufacture of claim 17, in which the solderable metal member comprises gold.

23. (new) The manufacture of claim 22, in which the solder member is substantially free of lead.